

Product Summary

BV_{DSS}	R_{DSON} Max	I_D Max T_C = +25°C
60V	50mΩ @ V _{GS} = 10V	18A
	63mΩ @ V _{GS} = 4.5V	16A

Description and Applications

This MOSFET is designed to minimize the on-state resistance (R_{DSON}), yet maintain superior switching performance, making it ideal for high efficiency power management applications.

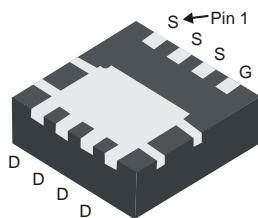
- Backlighting
- Power Management Functions
- DC-DC Converters

Features and Benefits

- Low R_{DSON} – Ensures On-State Losses are Minimized
- Small Form Factor Thermally Efficient Package Enables Higher Density End Products
- Occupies Just 33% of the Board Area Occupied by SO-8 Enabling Smaller End Product
- **Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)**
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability
- PPAP Capable (Note 4)

Mechanical Data

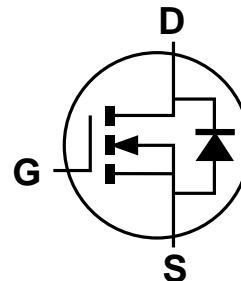
- Case: PowerDI®3333-8
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections Indicator: See Diagram
- Terminals: Finish — Matte Tin Annealed over Copper Leadframe. Solderable per MIL-STD-202, Method 208 (E3)
- Weight: 0.03 grams (Approximate)



Bottom View



Top View



Equivalent Circuit

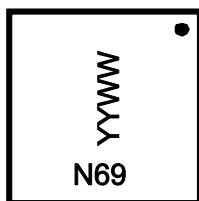
Ordering Information (Note 5)

Part Number	Case	Packaging
DMN6069SFGQ-7	PowerDI3333-8	2,000/Tape & Reel
DMN6069SFGQ-13	PowerDI3333-8	3,000/Tape & Reel

Notes:

1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
4. Automotive products are AEC-Q101 qualified and are PPAP capable. Refer to http://www.diodes.com/product_compliance_definitions.html.
5. For packaging details, go to our website at <http://www.diodes.com/products/packages.html>.

Marking Information



N69 = Product Type Marking Code
 YYWW = Date Code Marking
 YY = Last Two Digits of Year (ex: 16 = 2016)
 WW = Week Code (01 to 53)

Maximum Ratings (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)

Characteristic			Symbol	Value	Unit
Drain-Source Voltage			V_{DSS}	60	V
Gate-Source Voltage			V_{GSS}	± 20	V
Continuous Drain Current (Note 7) $V_{GS} = 10\text{V}$	Steady State	$T_A = +25^\circ\text{C}$ $T_A = +70^\circ\text{C}$	I_D	5.6 4.5	A
	Steady State	$T_C = +25^\circ\text{C}$ $T_C = +70^\circ\text{C}$	I_D	18 14.5	A
Pulsed Drain Current (380 μs Pulse, Duty Cycle = 1%)			I_{DM}	25	A
Maximum Continuous Body Diode Forward Current (Note 7)			I_S	2.5	A
Avalanche Current (Note 8) $L = 0.1\text{mH}$			I_{AS}	12	A
Repetitive Avalanche Energy (Note 8) $L = 0.1\text{mH}$			E_{AS}	7.2	mJ

Thermal Characteristics

Characteristic			Symbol	Value	Unit
Total Power Dissipation (Note 6)			P_D	0.93	W
Thermal Resistance, Junction to Ambient (Note 6)		Steady State	$R_{\theta JA}$	134	$^\circ\text{C}/\text{W}$
		$t < 10\text{s}$		82	
Total Power Dissipation (Note 7)			P_D	2.4	W
Thermal Resistance, Junction to Ambient (Note 7)		Steady State	$R_{\theta JA}$	53	$^\circ\text{C}/\text{W}$
		$t < 10\text{s}$		33	
Thermal Resistance, Junction to Case			$R_{\theta JC}$	5	
Operating and Storage Temperature Range			T_J, T_{STG}	-55 to +150	$^\circ\text{C}$

Notes:

- 6. Device mounted on FR-4 PC board, with minimum recommended pad layout, single sided.
- 7. Device mounted on FR-4 substrate PC board, 2oz copper, with thermal bias to bottom layer 1inch square copper plate.
- 8. I_{AS} and E_{AS} ratings are based on low frequency and duty cycles to keep $T_J = +25^\circ\text{C}$.

Electrical Characteristics ($T_A = +25^\circ\text{C}$, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 9)						
Drain-Source Breakdown Voltage	BV_{DSS}	60	—	—	V	$\text{V}_{\text{GS}} = 0\text{V}$, $\text{I}_D = 250\mu\text{A}$
Zero Gate Voltage Drain Current $T_J = +25^\circ\text{C}$	I_{DSS}	—	—	1	μA	$\text{V}_{\text{DS}} = 60\text{V}$, $\text{V}_{\text{GS}} = 0\text{V}$
Zero Gate Voltage Drain Current $T_J = +150^\circ\text{C}$	I_{DSS}	—	—	100	μA	$\text{V}_{\text{DS}} = 60\text{V}$, $\text{V}_{\text{GS}} = 0\text{V}$
Gate-Source Leakage	I_{GSS}	—	—	± 100	nA	$\text{V}_{\text{GS}} = \pm 20\text{V}$, $\text{V}_{\text{DS}} = 0\text{V}$
ON CHARACTERISTICS (Note 9)						
Gate Threshold Voltage	$\text{V}_{\text{GS(TH)}}$	1	—	3	V	$\text{V}_{\text{DS}} = \text{V}_{\text{GS}}$, $\text{I}_D = 250\mu\text{A}$
Static Drain-Source On-Resistance	$\text{R}_{\text{DS(ON)}}$	—	39	50	$\text{m}\Omega$	$\text{V}_{\text{GS}} = 10\text{V}$, $\text{I}_D = 4.5\text{A}$
		—	47	63		$\text{V}_{\text{GS}} = 4.5\text{V}$, $\text{I}_D = 3\text{A}$
Diode Forward Voltage	V_{SD}	—	—	1.1	V	$\text{V}_{\text{GS}} = 0\text{V}$, $\text{I}_S = 2.5\text{A}$
On State Drain Current (Note 10)	$\text{I}_{\text{D(ON)}}$	20	—	—	A	$\text{V}_{\text{DS}} \geq 5\text{V}$, $\text{V}_{\text{GS}} = 10\text{V}$
DYNAMIC CHARACTERISTICS (Note 10)						
Input Capacitance	C_{iss}	—	740	1,480	pF	$\text{V}_{\text{DS}} = 30\text{V}$, $\text{V}_{\text{GS}} = 0\text{V}$, $f = 1.0\text{MHz}$
Output Capacitance	C_{oss}	—	40	80	pF	
Reverse Transfer Capacitance	C_{rss}	—	28	55	pF	
Gate Resistance	R_g	—	2.2	4	Ω	$\text{V}_{\text{DS}} = 0\text{V}$, $\text{V}_{\text{GS}} = 0\text{V}$, $f = 1\text{MHz}$
Total Gate Charge ($\text{V}_{\text{GS}} = 4.5\text{V}$)	Q_g	—	6.4	12	nC	$\text{V}_{\text{DS}} = 30\text{V}$, $\text{I}_D = 12\text{A}$
Total Gate Charge ($\text{V}_{\text{GS}} = 10\text{V}$)	Q_g	—	14	25	nC	
Gate-Source Charge	Q_{gs}	—	2.8	5.5	nC	
Gate-Drain Charge	Q_{gd}	—	2.3	5	nC	
Turn-On Delay Time	$\text{t}_{\text{D(ON)}}$	—	3.6	10	ns	$\text{V}_{\text{DS}} = 30\text{V}$, $\text{I}_D = 12\text{A}$ $\text{V}_{\text{GS}} = 10\text{V}$, $\text{R}_g = 6.0\Omega$
Turn-On Rise Time	t_R	—	5.0	10	ns	
Turn-Off Delay Time	$\text{t}_{\text{D(OFF)}}$	—	12	24	ns	
Turn-Off Fall Time	t_F	—	3.3	10	ns	
Body Diode Reverse Recovery Time	t_{RR}	—	11	22	ns	$\text{I}_F = 4.5\text{A}$, $\text{di/dt} = 100\text{A}/\mu\text{s}$
Body Diode Reverse Recovery Charge	Q_{RR}	—	5.1	10	nC	

Notes: 9. Short duration pulse test used to minimize self-heating effect.

10. Guaranteed by design. Not subject to product testing.

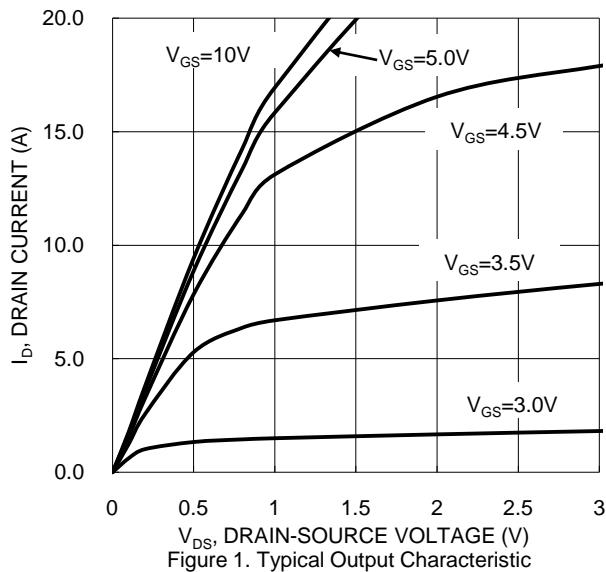


Figure 1. Typical Output Characteristic

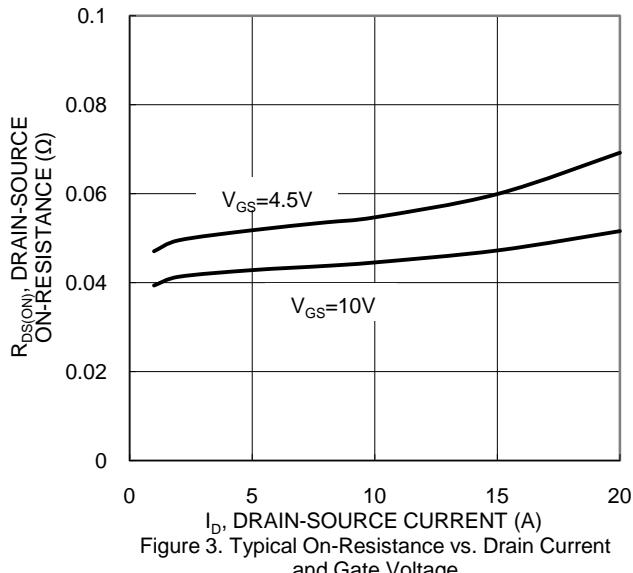


Figure 3. Typical On-Resistance vs. Drain Current and Gate Voltage

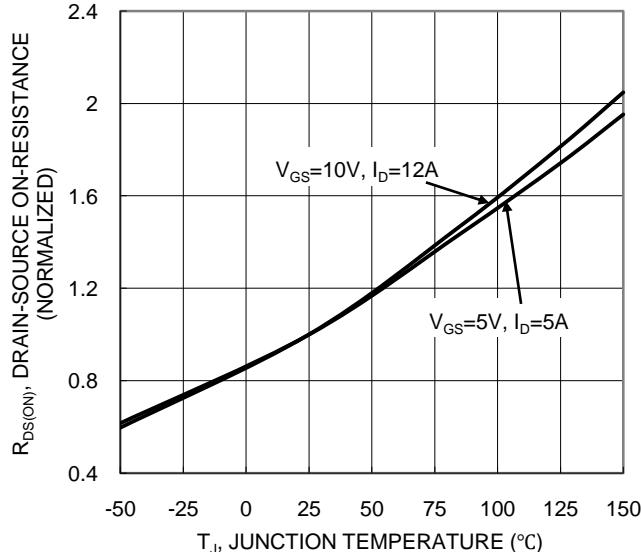


Figure 5. On-Resistance Variation with Temperature

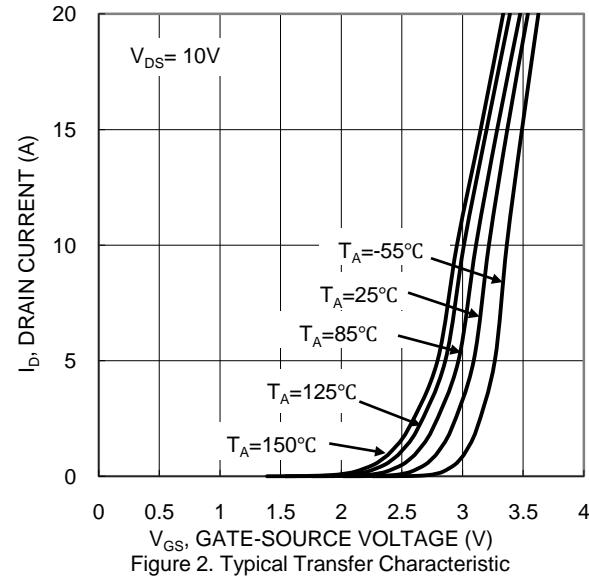


Figure 2. Typical Transfer Characteristic

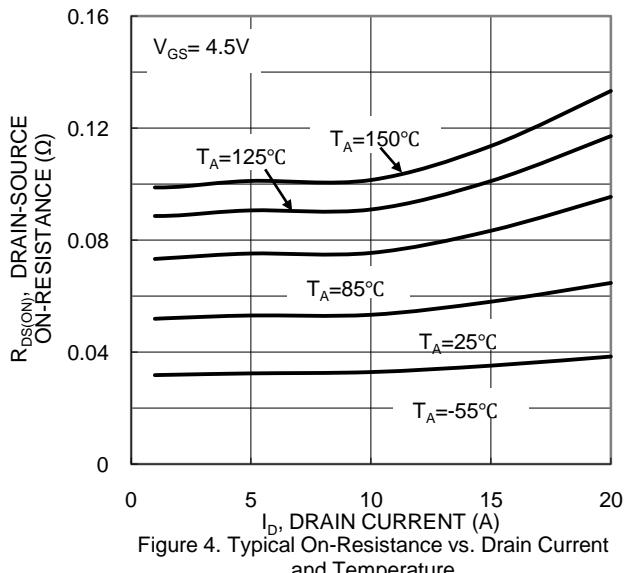


Figure 4. Typical On-Resistance vs. Drain Current and Temperature

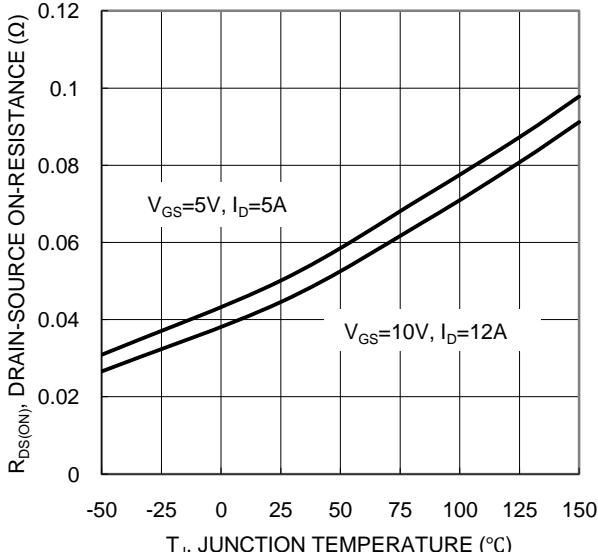
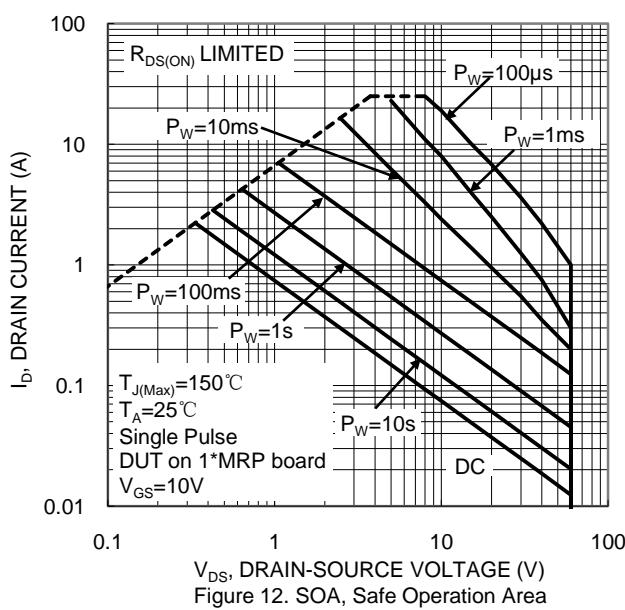
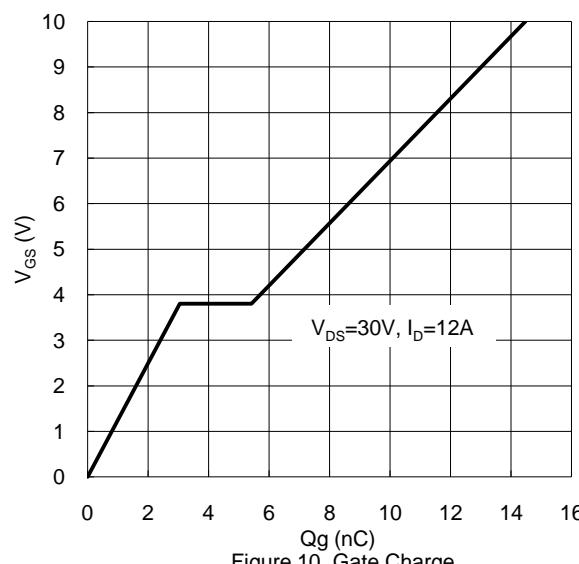
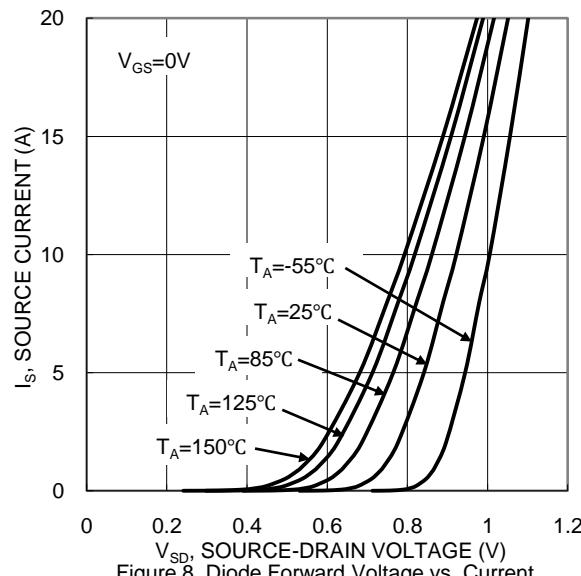
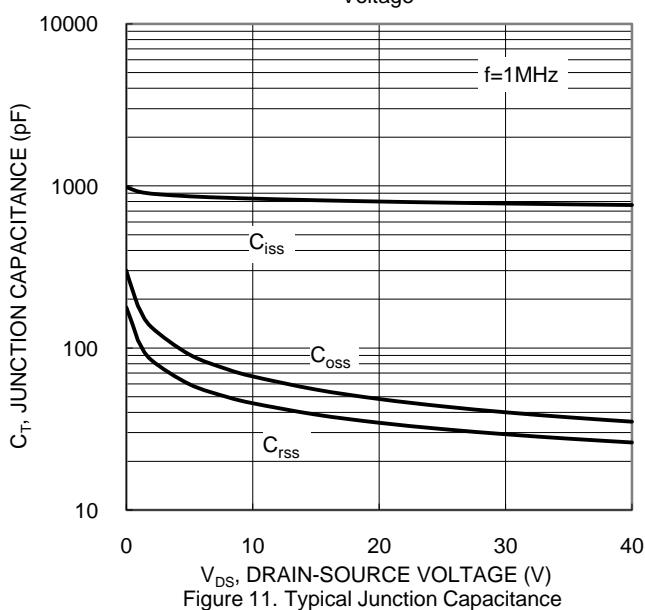
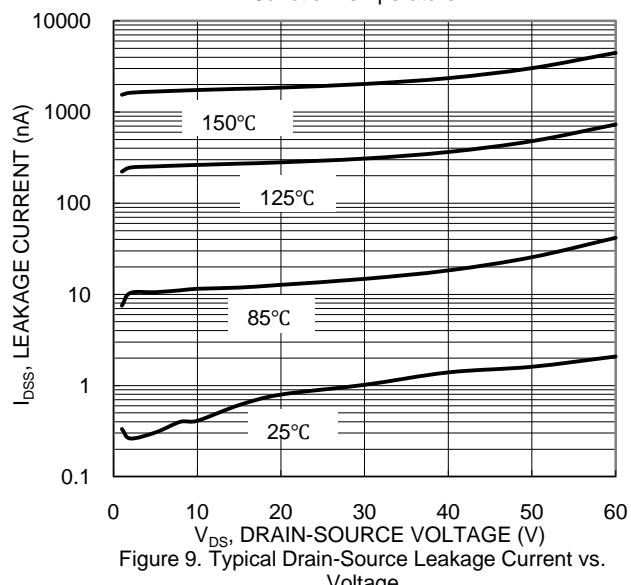
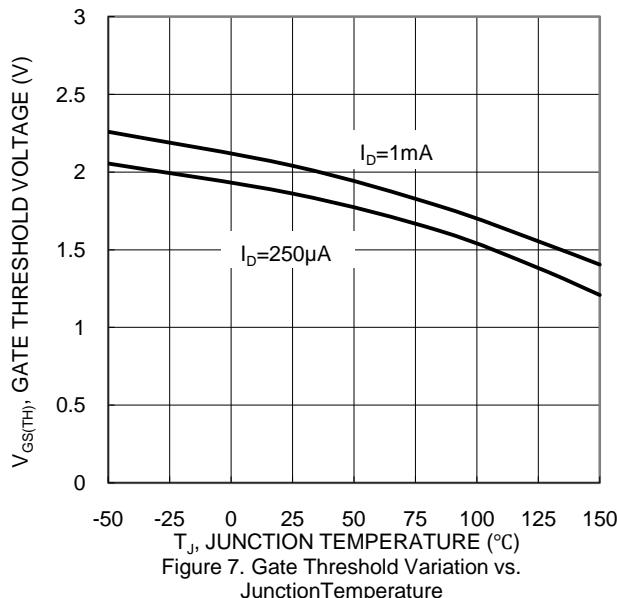


Figure 6. On-Resistance Variation with Temperature



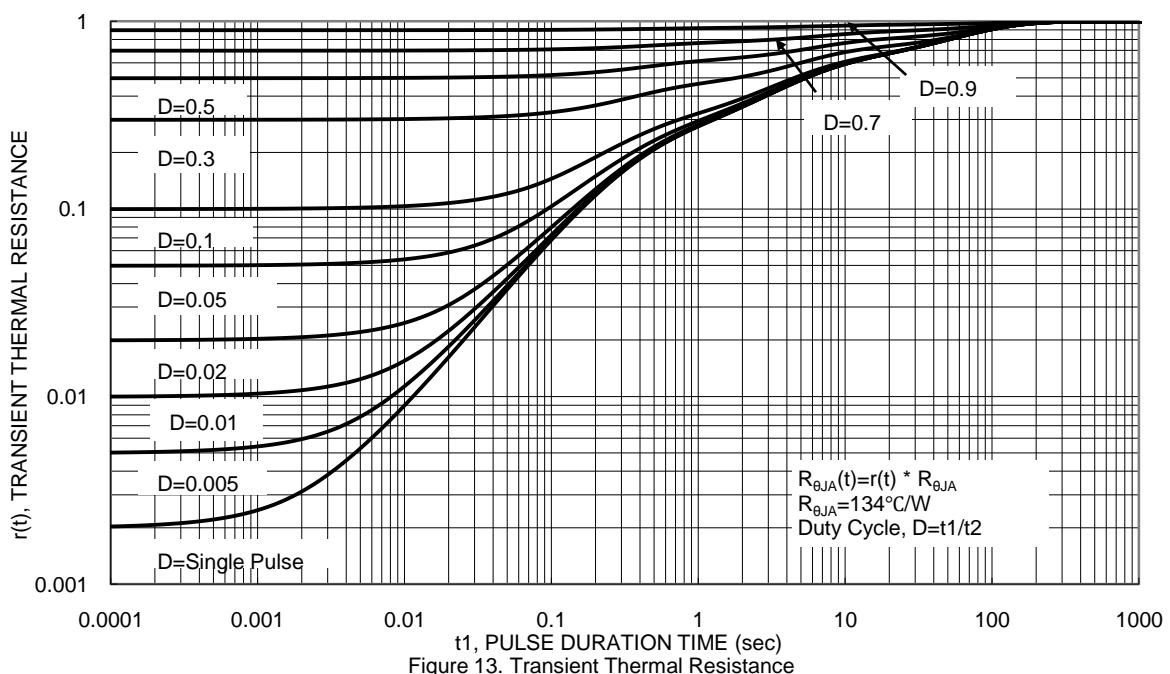
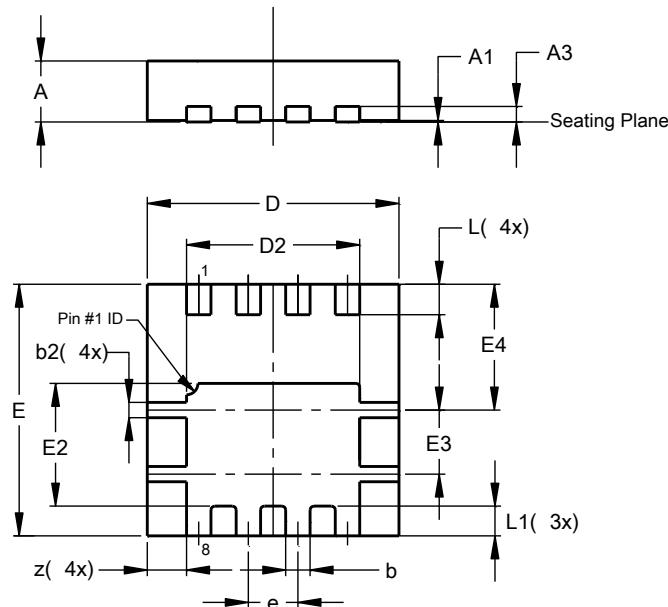


Figure 13. Transient Thermal Resistance

Package Outline Dimensions

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

PowerDI3333-8



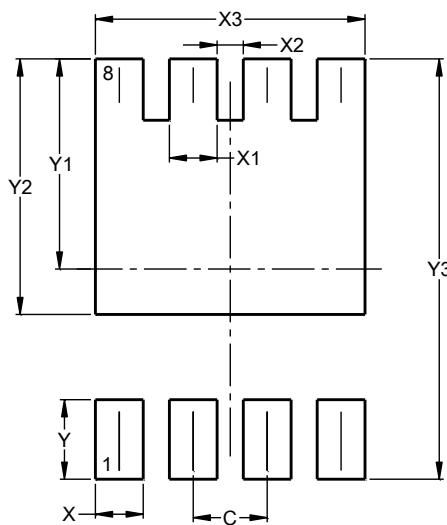
PowerDI3333-8			
Dim	Min	Max	Typ
A	0.75	0.85	0.80
A1	0.00	0.05	0.02
A3	—	—	0.203
b	0.27	0.37	0.32
b2	0.15	0.25	0.20
D	3.25	3.35	3.30
D2	2.22	2.32	2.27
E	3.25	3.35	3.30
E2	1.56	1.66	1.61
E3	0.79	0.89	0.84
E4	1.60	1.70	1.65
e	—	—	0.65
L	0.35	0.45	0.40
L1	—	—	0.39
z	—	—	0.515

All Dimensions in mm

Suggested Pad Layout

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

PowerDI3333-8



Dimensions	Value (in mm)
C	0.650
X	0.420
X1	0.420
X2	0.230
X3	2.370
Y	0.700
Y1	1.850
Y2	2.250
Y3	3.700

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